

Apparatus and Associated Method for Conditioning in Chemical Mechanical Planarization

ABSTRACT OF THE DISCLOSURE

5 A conditioning apparatus for use in a CMP system is provided along with an
associated method of operation. The conditioning apparatus includes rotation mechanics
and oscillation mechanics. The rotation mechanics are capable of rotating a shaft which
causes a holder and a conditioning substrate to be rotated. The oscillation mechanics are
capable of moving a position of the shaft within a region defined by a peripheral boundary
10 that is less than and within an outer periphery of the conditioning substrate. A conditioning
substrate backing is also included in the conditioning apparatus. The conditioning substrate
backing defines a differential pressure distribution that is capable of being applied to the
conditioning substrate.